



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

ATTY.'S DOCKET: 98 P 7501 US 01

*Handwritten: #21 HAVE*

re the application of: )  
Ramachandran et al. ) Group Art: 1746  
Serial No.: 09/204,706 ) Examiner: A. Olsen  
Filing Date: December 3, 1998 )  
Title: REMOVAL OF POST-RIE POLYMER) ON Al/Cu METAL LINE )

*Do Not Enter  
As of 8/6/03*

AMENDMENT UNDER 37 C.F.R. §1.116

Commissioner For Patents  
P.O. Box 1450  
Arlington, VA 22313-1450

Sir:

Responsive to the Office Action of September 10, 2002,  
please amend the application as follows:

IN THE CLAIMS:

13. (5th Amendment) In a metal etch tool for removing  
post-RIE polymer rails formed on a Al/Cu metal line of a  
semiconductor structure, the improvement comprising:

[I] an integrated metal etch tool interfaceable with:

a) strip chamber means [for water only plasma] to strip  
photo-resist of a semiconductor composite structure subsequent  
to a RIE to limit thickness of sidewall polymer rails;

b) vacuum chamber means to chemically modify sidewall  
polymer rails [by supplying a mixture of an etching gas/acid  
neutralizing gas of HF/NH<sub>3</sub>] to form a water soluble residue  
material of sidewall polymer rails left behind on [the] a  
Al/Cu metal line from the RIE process; and

c) deionized water rinse chamber means to [remove]  
rinse [water] soluble material.

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